

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2905587

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SSU-CHIANG WENG	06/12/2014
KUO-CHENG LEE	06/12/2014
CHI-CHERNG JENG	06/12/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13968260
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.2570
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	06/19/2014
Total Attachments: 2	
source=2570-assignment#page1.tif	
source=2570-assignment#page2.tif	

Docket No.: 2013-0517/24061.2570
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- (1) Ssu-Chiang Weng of 9F, No.110, Section 1, Zhongshan Road
Yonghe District
New Taipei City 234, Taiwan, R.O.C.
- (2) Kuo-Cheng Lee of No. 31, Dongqiao 8th Street
Yongkang District
Tainan City 710, Taiwan, R.O.C.
- (3) Chi-Cherng Jeng of No. 326, Keziliao
Madou Township
Tainan County 721, Taiwan, R.O.C.

have invented certain improvements in

STRUCTURE OF DIELECTRIC GRID WITH A METAL PILLAR FOR SEMICONDUCTOR DEVICE

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on August 15, 2013, and assigned application number 13/968,260; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., (“TSMC”), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2013-0517/24061.2570

Customer No.: 000042717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ssu-Chiang Weng

Residence Address: 9F, No.110, Section 1, Zhongshan Road, Yonghe District
New Taipei City 234, Taiwan, R.O.C.

Dated: 2014/6/12

Ssu-Chiang Weng
Inventor Signature

Inventor Name: Kuo-Cheng Lee

Residence Address: No. 31, Dongqiao 8th Street, Yongkang District
Tainan City 710 Taiwan, R.O.C.

Dated: 2014/6/12

KUO-CHENG LEE
Inventor Signature

Inventor Name: Chi-Cherng Jeng

Residence Address: No. 326, Keziliao, Madou Township
Tainan County 721 Taiwan, R.O.C.

Dated: 2014.6.12

Chi-Cherng Jeng
Inventor Signature